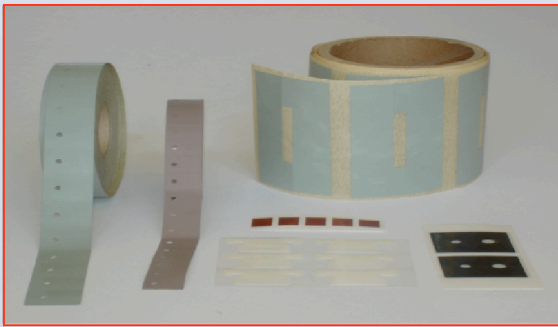


TIM-PAD is designed to meet industry's rapidly growing need for interface material with high thermal conductivity and insulating properties. For a wide range of applications, TIM-PAD is a clean, production friendly and efficient alternative to mica, ceramics or grease and will provide superb protection against damage due to deformation as well as shock or vibration.



TIM-PAD

Thermally Conductive, Insulating Pads

PROPERTY	TEST METHOD	1001	1002	1003
Type		Silicone	Silicone	Silicone
Color	Visual	Gray	Brown	White
Reinforcement Carrier		Fiberglass	Fiberglass	Fiberglass
Thickness, mm		0.15	0.15	0.20
Hardness, (Shore Type A)	ASTM D2240	86	93	84
Tensile Strength, KN/m	KN/m	11	8	15
Elongation, %		<2	<2	<3
Thermal Conductivity W/m ² k	ASTM D5470 Modified	1.1	1.6	3.0
Thermal Impedance °CIn ² /W	ASTM D5470 Modified	0.51	0.55	0.30
Thermal Impedance with PSA °CIn ² /W	ASTM D5470 Modified	0.78	0.63	0.64
Volume Resistivity, Ohm-cm	ASTM D257	10 ¹⁵	10 ¹⁵	10 ¹⁵
Dielectric Constant	ASTM D150	2.5	3.0	26
Dielectric Breakdown voltage	ASTM D149	4000	2000	3000
Flame Retardancy		V-O	V-O	V-O
Available Thickness, mm		0.15, 0.20 0.30	0.15, 0.20 0.30	0.20, 0.30 0.45, 0.85

Availability:

- **TIM-PADS** are available in die-cut or sheet form with protective liners on both sides. The material is compatible with dispensing equipment for high volume production.
- Materials are available standard and/or special shape and size. Tooling charges vary depending on tolerances and complexity of the part
- **TIM-PAD** materials are available with or without adhesive for easy of handling and installation in standard or complex assemblies

Key Features

- High Thermal Conductivity up to 3.0 W/m²K
- Eliminates the mess of grease
- Clean and easy to apply
- Resistance to electrical shorting
- Reinforcements to resist cut-through
- Re-workable/Clean release from device
- Variety of thicknesses
- Available with or without adhesive coating

Applications

- Interface for discrete semiconductors requiring low pressure or spring clamp mounting
- Isolate power sources and electrical components from heat sink/or mounting bracket
- Medical devices
- Between CPU and Heat Spreader
- Consumer electronics
- Industrial controls

Disclaimer: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent